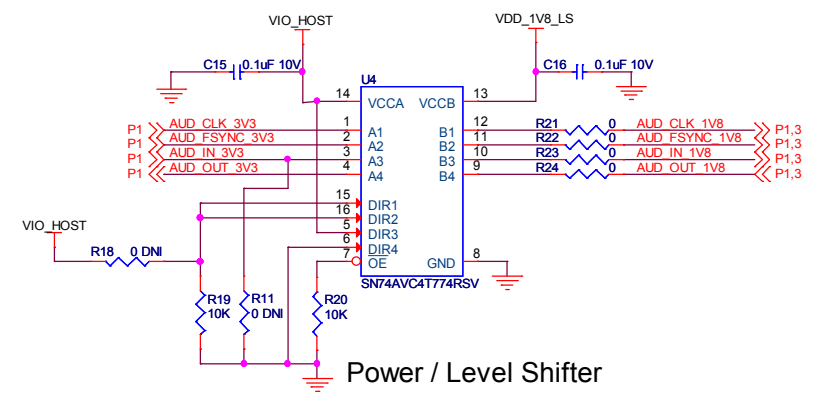
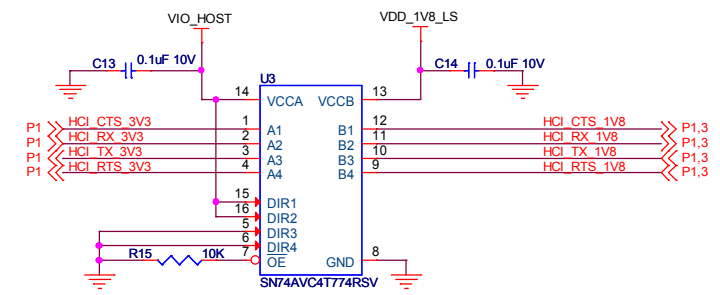
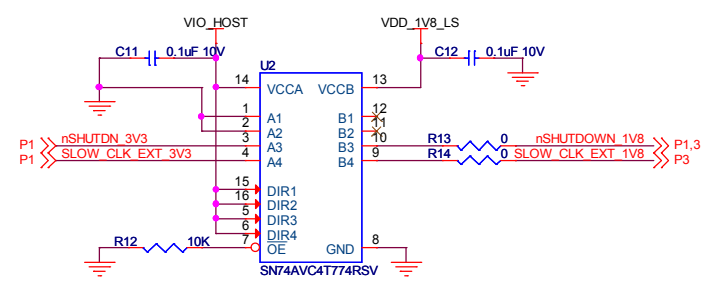


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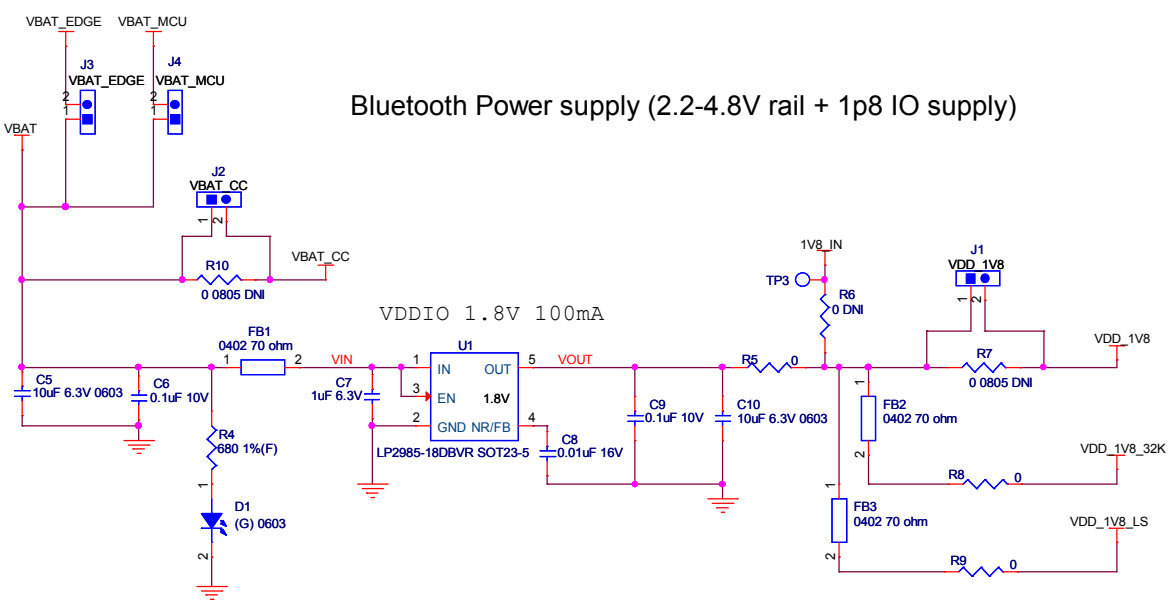
Level Shifters

"H" A->B
 "L" B->A



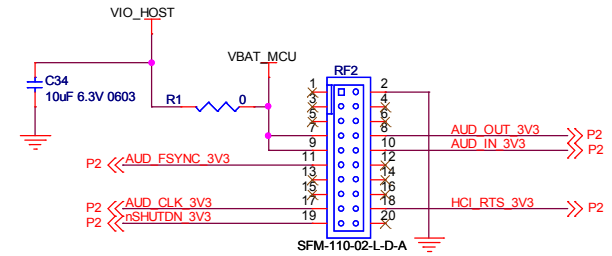
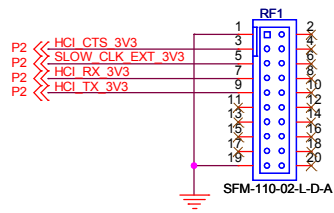
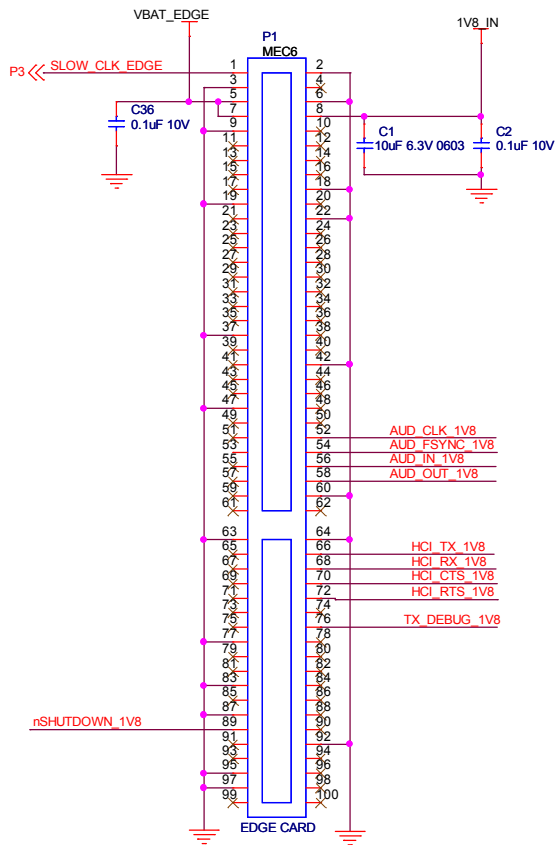
Power / Level Shifter

Bluetooth Power supply (2.2-4.8V rail + 1p8 IO supply)



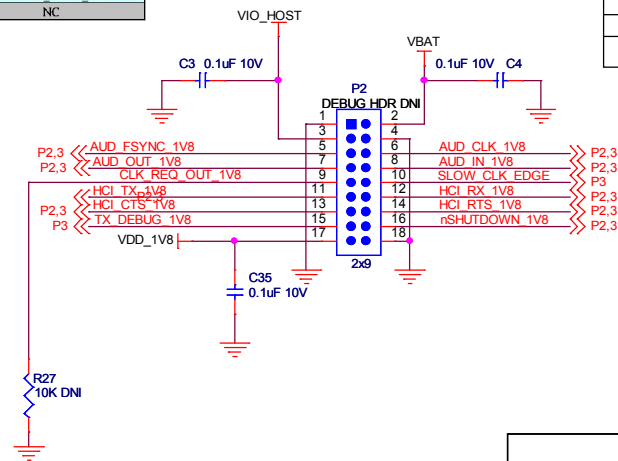
Configuration Notes:			
	01-EM	02-COM	
J3	OPEN	Install	
J4	Install	OPEN	

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RF1 Connector		RF2 Connector	
PINS	EM Adapter Assignment	PINS	EM Adapter Assignment
1	GND	1	NC
3	MODULE_UART_CTS	3	NC
5	SLOW_CLK	5	NC
7	MODULE_UART_RX	7	3.3V
9	MODULE_UART_TX	9	3.3V
11	NC	11	MODULE_AUDIO_FSYNC
13	NC	13	NC
15	NC	15	NC
17	NC	17	MODULE_AUDIO_CLK
19	GND	19	nSHUTD
2	NC	2	GND
4	NC	4	NC
6	NC	6	NC
8	NC	8	MODULE_AUDIO_DATA_OUT
10	NC	10	MODULE_AUDIO_DATA_IN
12	NC	12	NC
14	NC	14	NC
16	NC	16	NC
18	NC	18	MODULE_UART_RTS
20	NC	20	NC

Configuration Notes:		
	01-EM	02-COM
RF1	Install	Removed
RF2	Install	Removed



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